

## DialogIP

**EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE**

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**International Class:**

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**Abstract:**

**PROBLEM TO BE SOLVED:** To obtain an epoxy resin composition for sealing a semiconductor which does not contain a halogen-containing flame-retardant and an antimony compound and is excellent in molding properties, flame retardancy, high temperature storage characteristics, moisture resistance reliability and solder crack resistance. **SOLUTION:** The epoxy resin composition for sealing a semiconductor comprises, as essential ingredients, (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator, (D) an inorganic filler and (E) a metal hydroxide solid solution represented by the general formula:  $Mg_{1-x}M2_x(OH)_2$  (wherein  $M2^+$  is at least one divalent metal ion selected from the group consisting of  $Mn^{2+}$ ,  $Fe^{2+}$ ,  $Co^{2+}$ ,  $Ni^{2+}$ ,  $Cu^{2+}$  and  $Zn^{2+}$ ; and (x) is a number of  $0.01 \leq x \leq 0.5$ ), and the specific surface area of the metal hydroxide solid solution represented by the general formula is 1.5-4.5 m<sup>2</sup>/g. **COPYRIGHT:** (C)2001,JPO

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